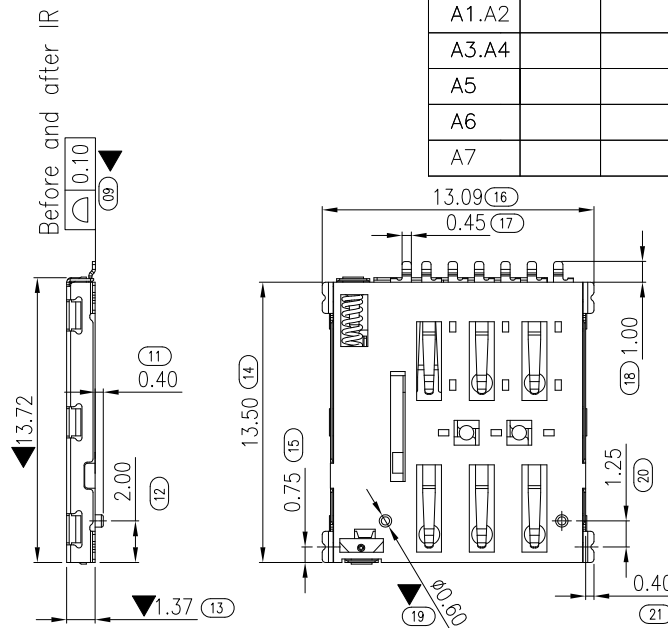
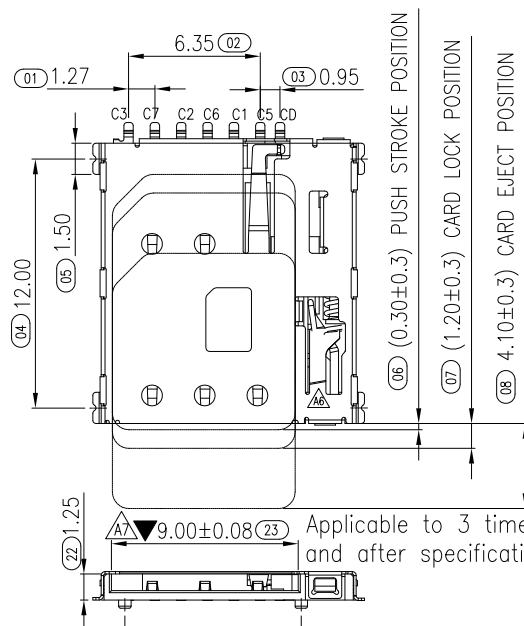


GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2016/10/27	Phebe Su
A1.A2			Update.Change housing	2016/10/28.2016/12/22	Phebe Su
A3.A4			Modify.Change	2017/06/06.2017/07/07	Phebe Su
A5			Add the focus size mark	2017/12/01	Phebe Su
A6			Change angle of Slider	2017/12/07	Summer Wang
A7			Change 8.90 to 9.0±0.08	2018/01/10	Phebe Su



Specification:

MATERIAL:

Insulator: High Temperature Thermoplastic, UL 94V-0. Black

Contact: Copper Alloy

SHELL: STANLESS STEEL

PLATING:

Contact Area: Au 30u".

Solder Area: Matte tin plated. Under plate: nickel.

Shell: Nickel plated over all.

Solder Area: Gold flash.

Electrical:

Current Rating :1.0A max.

Voltage Rating :30V

Ambient Temperature Range : -40°C $+85^{\circ}\text{C}$

Storage Temperature Range : $-40^{\circ}\text{C} \sim +85^{\circ}\text{C}$

Humidity: 80% R. H. Max.

Contact Resistance: $50\text{m}\Omega_{\text{max}}$.

Insulation Resistance:1000M Ω MIN 500V DC

Mating Cycles:5,000 Insertions

Solder ability: $260 \pm 0/-5^{\circ} \text{C. } 30 \pm 10 \text{s.}$

Add the focus size mark ▼

MATRIX PART NO:

Matrix NANO SIM

MSM - 01 - 30 - 06 - 13 - 23

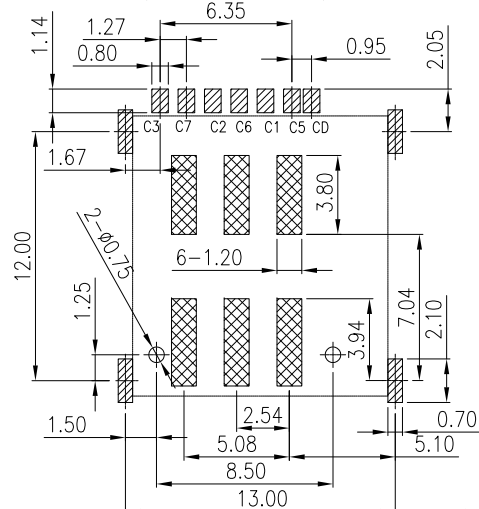
01: Push
02: Non-Push

Plating
01: G/F
30: 30u

Series Number

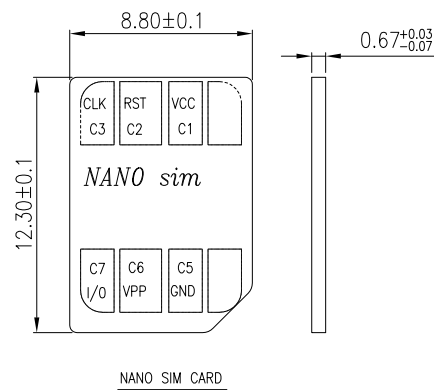
Height

Pin number
06: 6pin

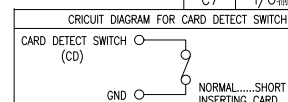


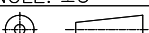
RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ± 0.05

 PAD
 KEEP OUT AREA



SIM pin assignment	
PIN#	Name
C1	VCC供电电压
C2	RST重置
C3	CLK时钟
C5	GND接地
C6	VPP程序电压
C7	I/O输入输出



NO	VARIETY	QTY	MATERIAL	REMARK	
 Matrix Electronics Co.,Ltd					
TOLERANCE: X.X X.XX ±0.30 X.XXX ±0.20 X.XXX ±0.10 ANGLE: ±3°		DESIGN BY : Phebe Su	DATE : 2018/01/10	PART NAME: NANO-SIM PUSH/PUSH 1.35H	
		CHECKED BY: Vicky Hsieh	DATE : 2018/01/10	PART NO.	MSM-01-30-06-13-23
		APPROVED BY1: Richard Hsieh	DATE : 2018/01/10	MOLD NO.	NA
UNIT: mm [inch]		APPROVED BY2: Richard Hsieh	DATE : 2018/01/10	DRAW NO.	
SCALE:1:1	SIZE:A4			SHEET NO.	1 OF 1